

IBM-POU920020057US1 Examiner D.D.Nguyen,
10/755922

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D: Remarks:

The amendment is made to point out the the claimed flex film interposer is an integrated element providing a Land Grid Array (LGA) electrical connection disposed between a Multi-Chip Module (MCM) and the next level of integration such of a Land Grid Array system and said flex film, wherein said interposer also provides means integral to said flex film interposer for implementing a desired Engineering Change (EC) and said flex film interposer also integrally provides means for decoupling power to ground in the Land Grid Array structure to minimize switching activity effects on the Land Grid Array system when mounted on a system board between the system board and the Multi-Chip Module.

The primary reference Tamarkin et al 6428327 provides (as the examiner interprets this) 400/500 which is not a chip to module interposer, and so does not provide a decoupling power to ground decoupling when mounted on a system board. Furthermore 400/500 is not a flex film, and it is not an interposer because the interposer is element 330.

The interposer 50 of the secondary reference is not between the system board and the module.

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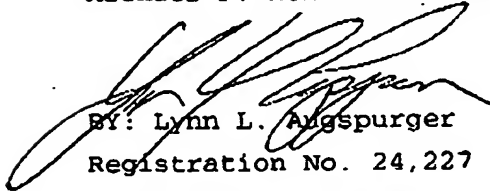


Reconsider is requested at this time, and a notice of allowance is deemed appropriate.

RESPECTFULLY SUBMITTED

(For the inventors)

Michael F. McAllister and John G. Torok


BY: Lynn L. Augspurger
Registration No. 24,227
Phone: 845-433-1174
Fax: 845-432-9601

Mailing Address:

IBM Intellectual Property Law
2455 South Road, P386
Poughkeepsie, NY 12601

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